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JC987

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10002724	FILING DATE 10 25 2001	CLASS 438	SUBCLASS	GAU 2812	EXAMINER
**APPLICANTS: Madrid Ruben Palacpac Diosdado.					
**CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/257,939 12/21/2000					
**FOREIGN APPLICATIONS VERIFIED:					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO TI-27987	
TITLE : Method and system for manufacturing ball grid array ("BGA") packages					

PTO-2040
12/99

NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner		DRAWING	
Amount Due	Date Paid			Sheets Drwg.	Figs.Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

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